

**THIN INTEGRATED CIRCUIT PACKAGE HAVING AN OPTICALLY TRANSPARENT
WINDOW**

ABSTRACT OF THE DISCLOSURE

A thin integrated circuit package having an optically transparent window provides a small profile optical integrated circuit assembly for use in digital cameras, video cellular telephones and other devices requiring a small physical size and optical integrated circuit technology. A tape having a conductive metal layer on a surface is used to interface the optical integrated circuit die with electrical interconnects disposed on a surface of the tape opposite the die. A supporting structure surrounds the die and a glass cover is either bonded to the top of the supporting structure over the die, or the glass cover is bonded to the top of the die and the gap between the glass cover and supporting structure filled with encapsulant. The resulting assembly yields a very thin optical integrated circuit package.